

Impedance Profile

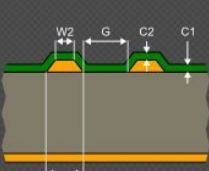
Description: diff1

Type: Differential

Target Impedance: 100

Target Tolerance: 10%

Transmission Line



Simulated with SIMBEOR® software

Use Solder Mask: ☒

Trace Inverted: ☐

Etch (Z): 0

Width (W1): 0.24132mm

Width (W2): 0.24132mm

Covering (C1): 0.0127mm

Covering (C2): 0.0127mm

Trace Gap (G): 0.2mm

Impedance (Zdiff): 99.98

Deviation: 0.02%

Delay (Tp): 5.67449ns/m

Inductance: 567.24685nH/m

Capacitance: 56.76082pF/m

Impedance Profile

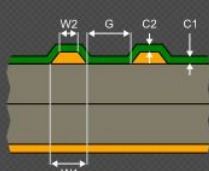
Description: diff2

Type: Differential

Target Impedance: 120

Target Tolerance: 10%

Transmission Line



Simulated with SIMBEOR® software

Use Solder Mask: ☐

Trace Inverted: ☐

Etch (Z): 0

Width (W1): 0.29395mm

Width (W2): 0.29395mm

Covering (C1): 0.0127mm

Covering (C2): 0.0127mm

Trace Gap (G): 0.2mm

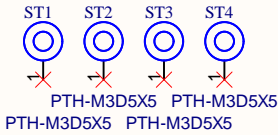
Impedance (Zdiff): 120.05

Deviation: 0.04%

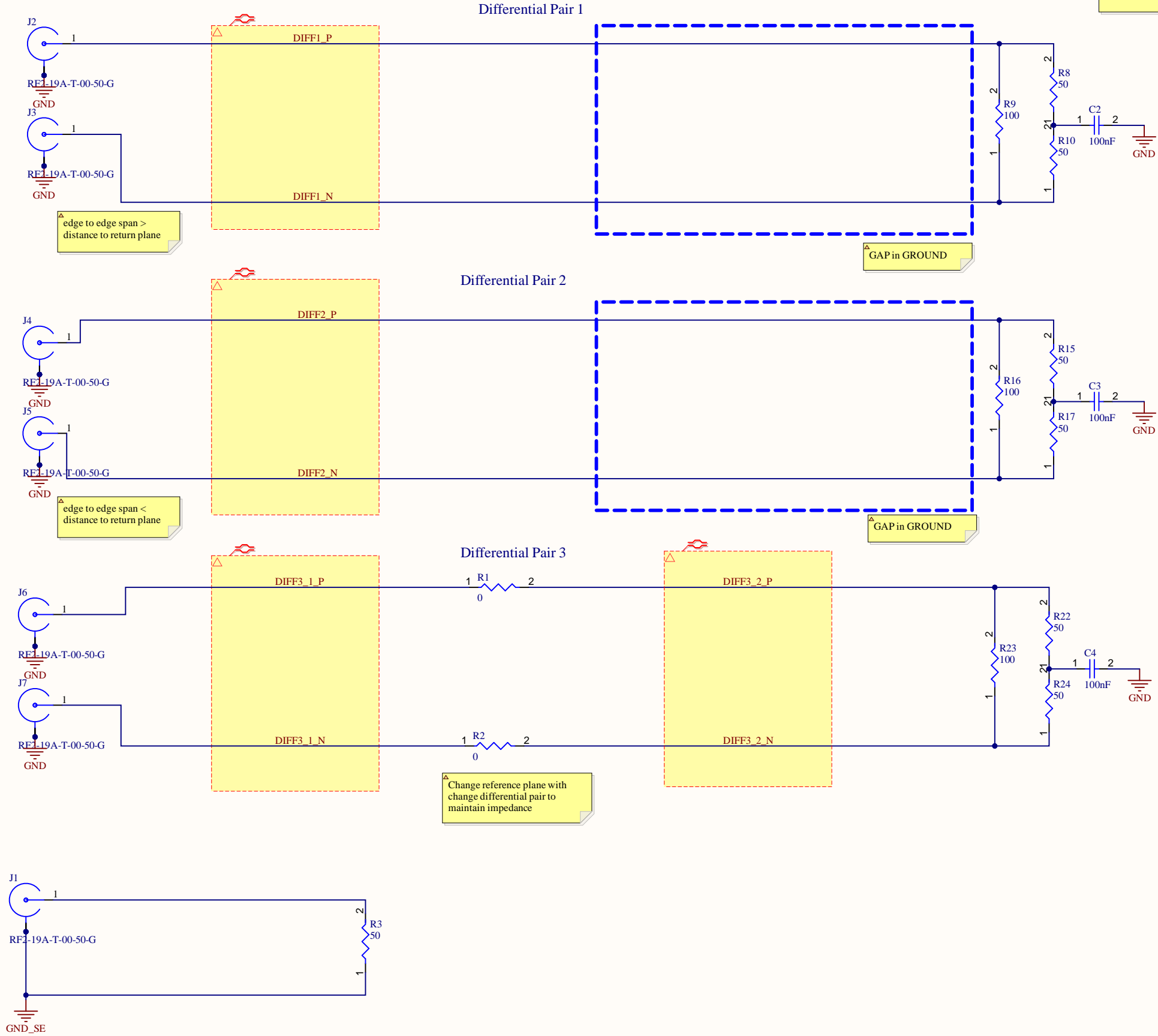
Delay (Tp): 5.27201ns/m

Inductance: 632.87657nH/m

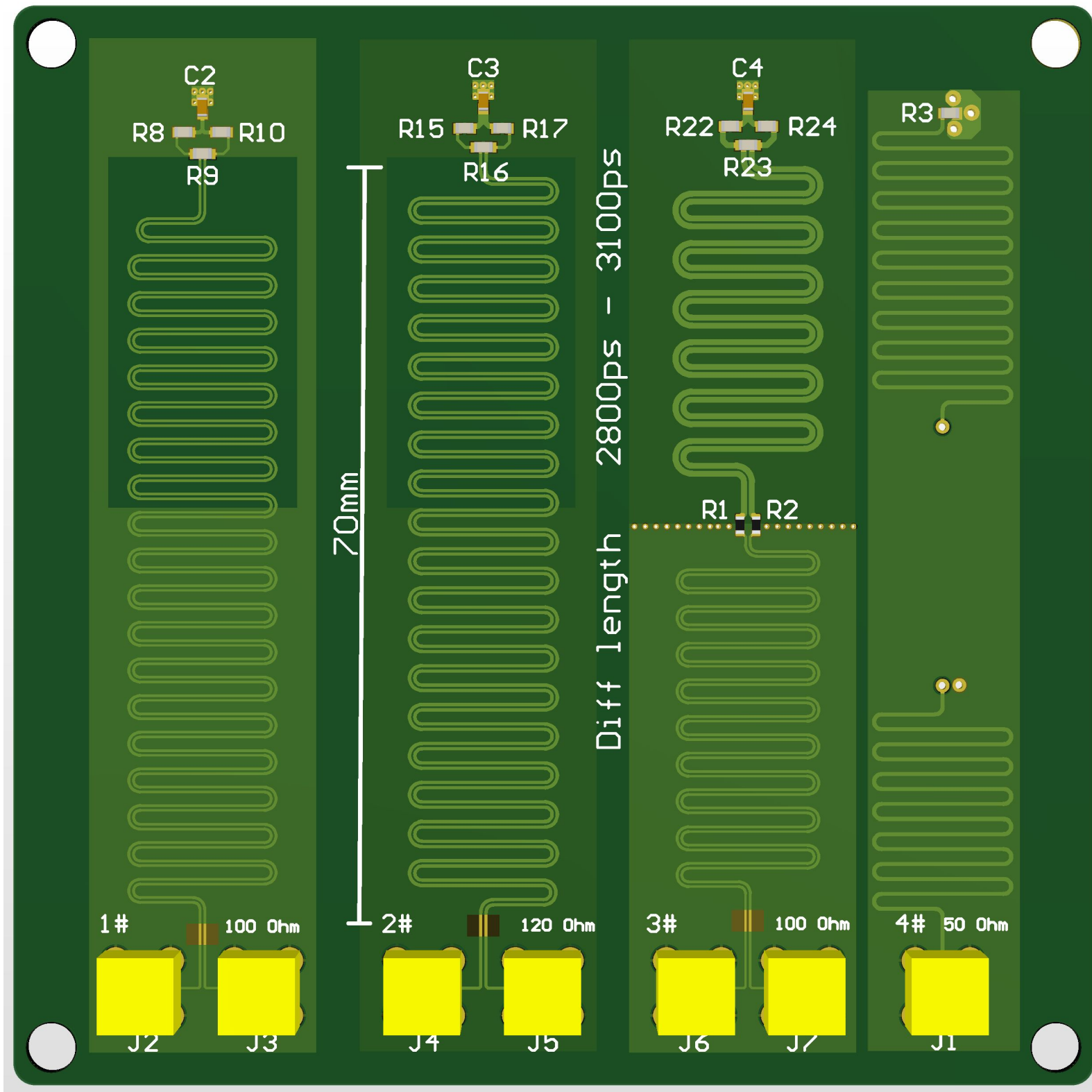
Capacitance: 43.91525pF/m

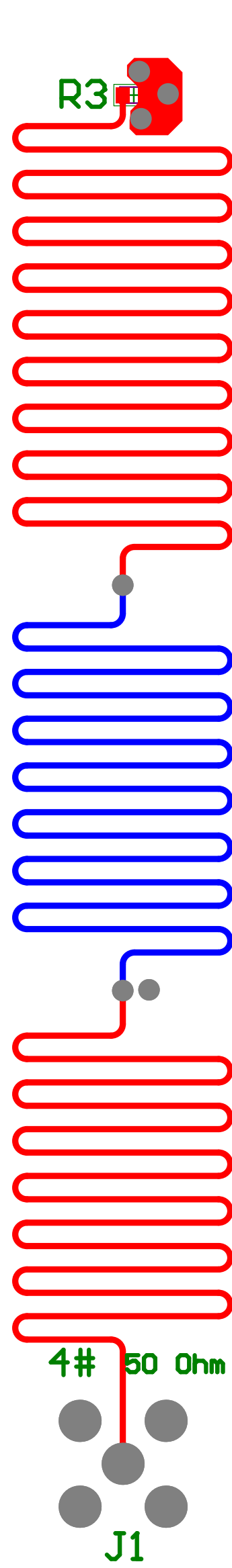
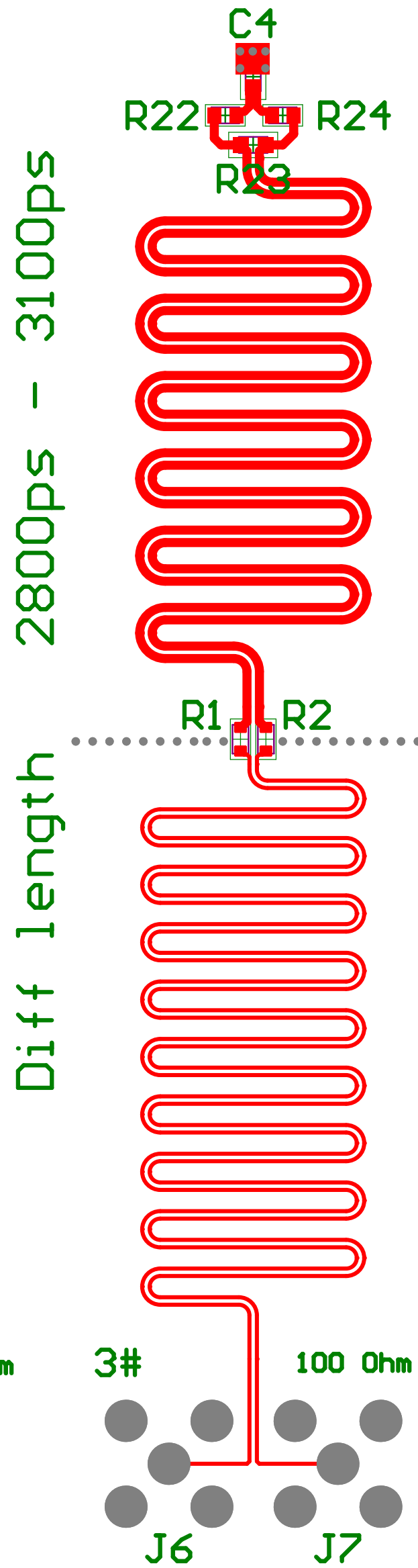
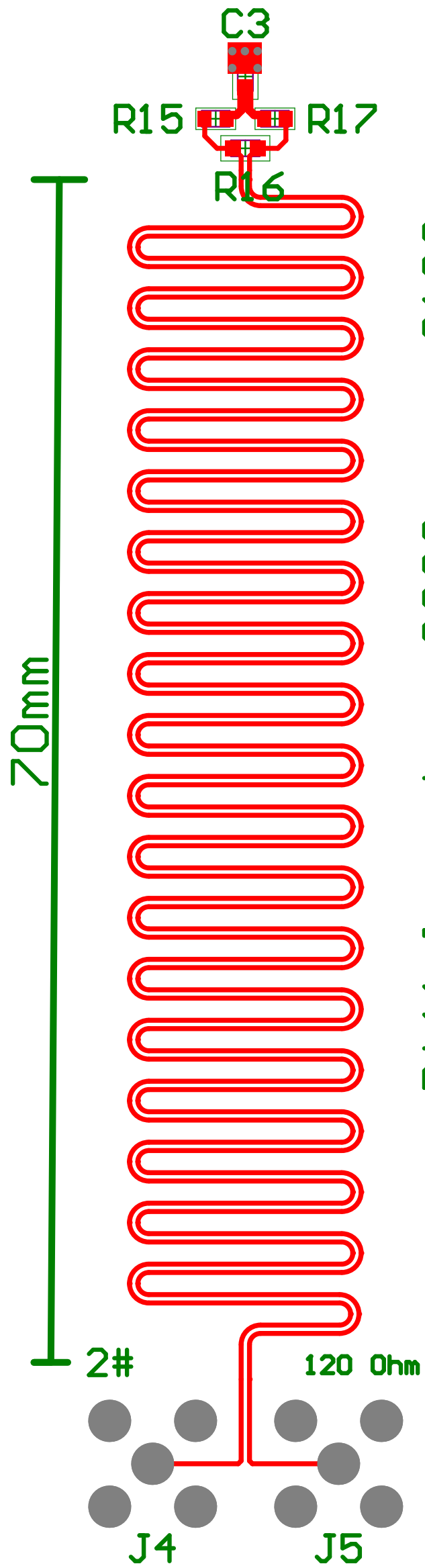
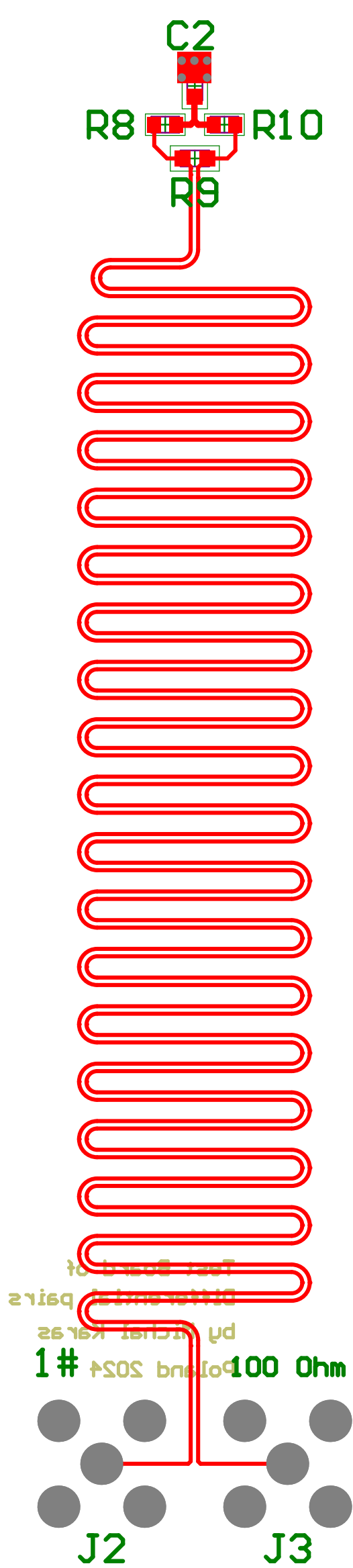


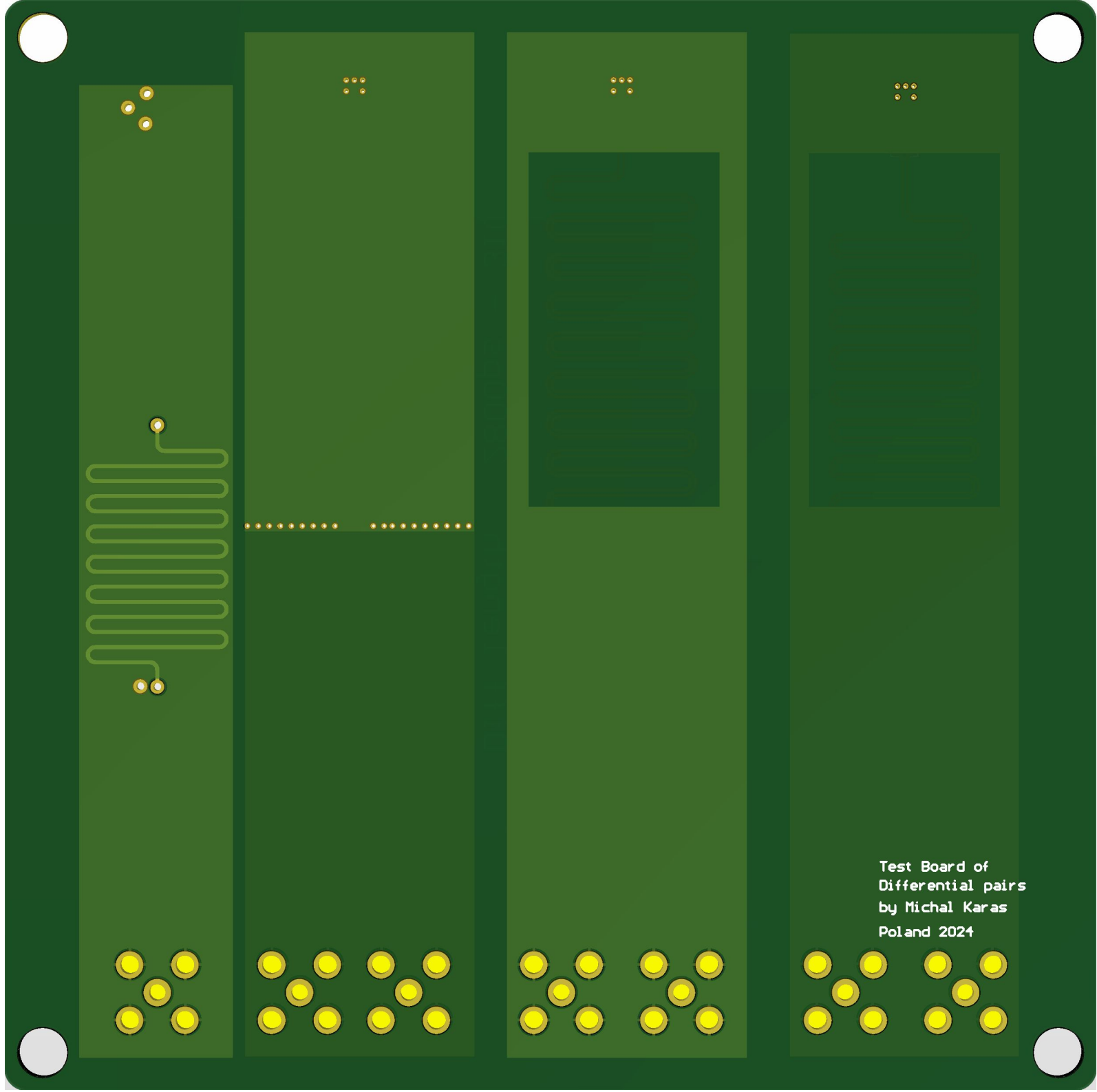
# TEST Board



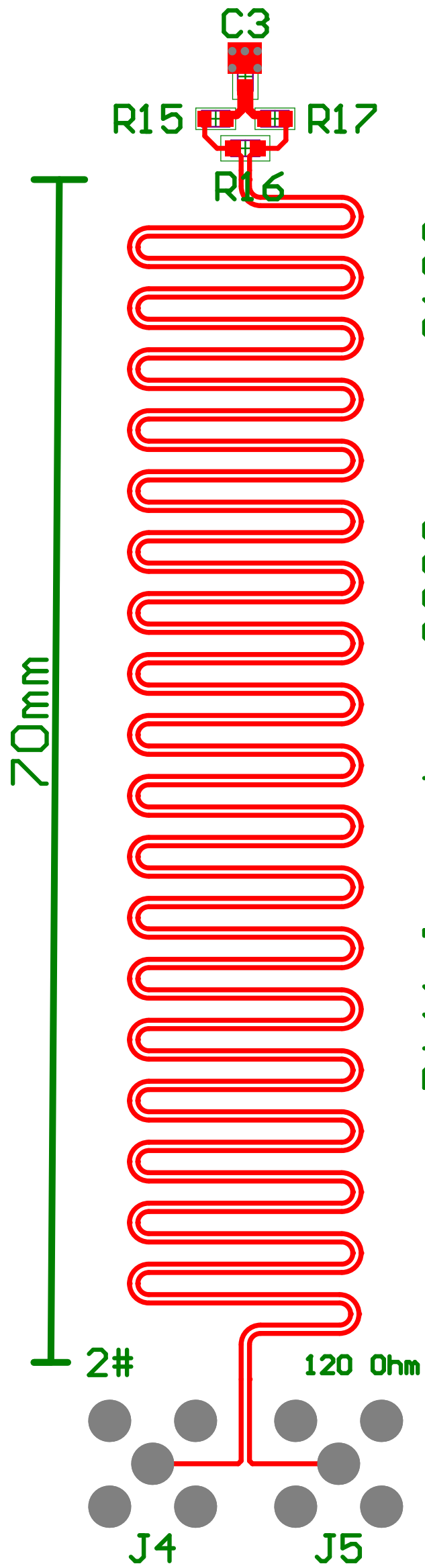
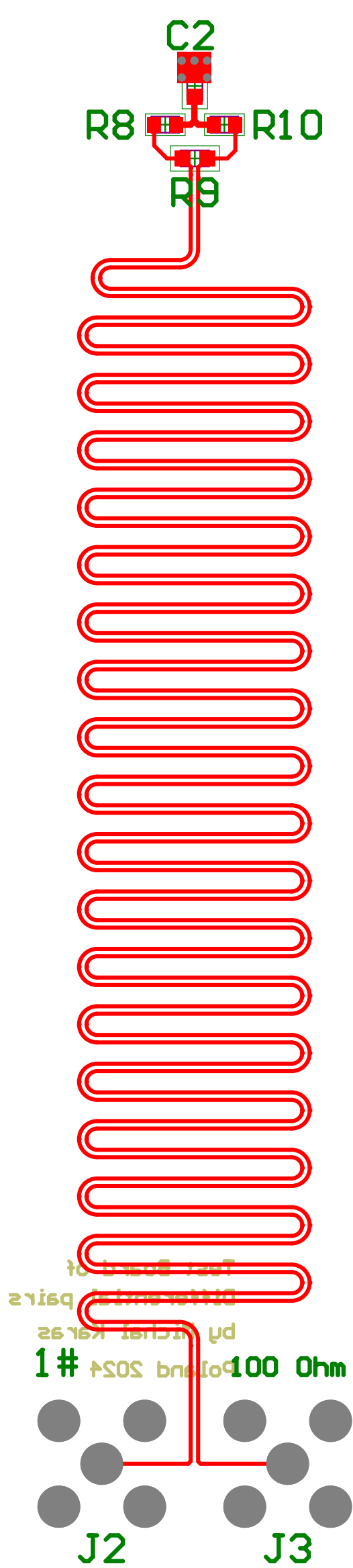
Title		
Size	Number	Revision
A3		
Date:	9.06.2024	Sheet of
File:	C:\Users\...\Test Board.SchDoc	Drawn By:



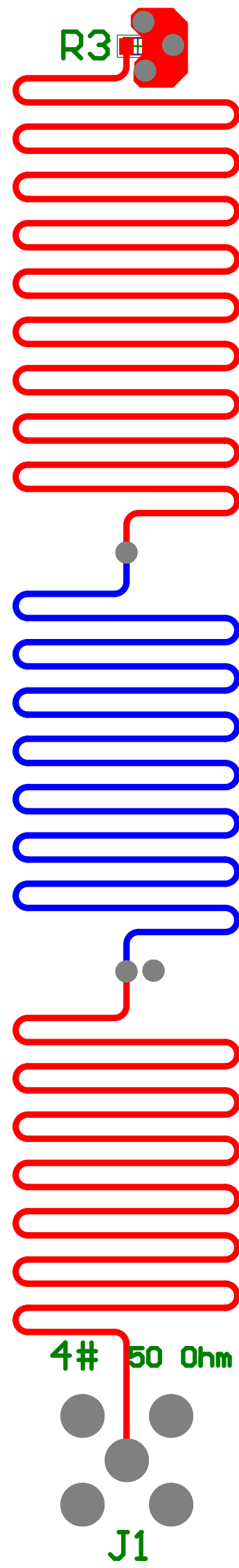
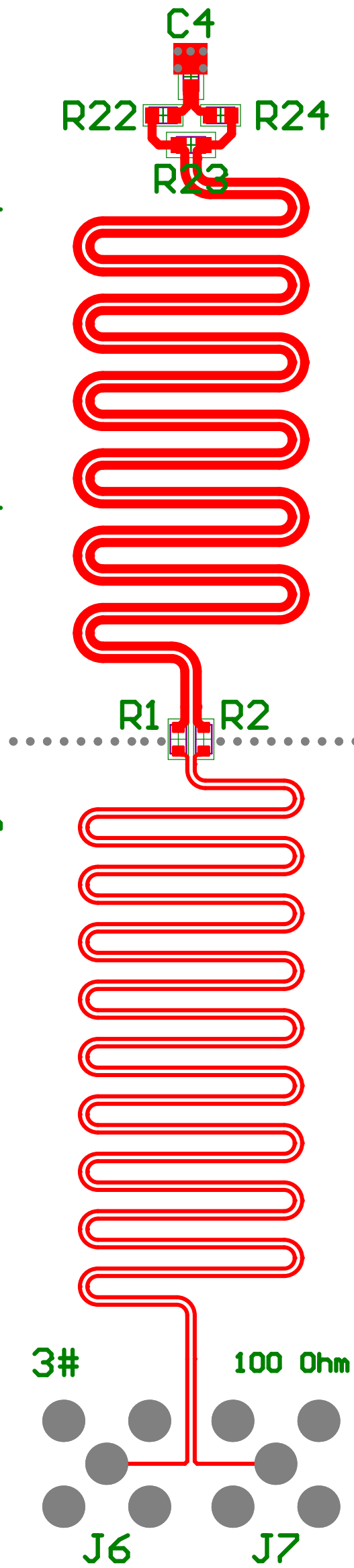


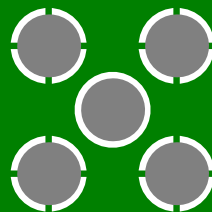
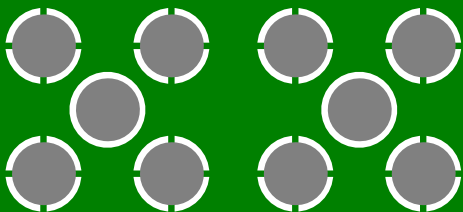
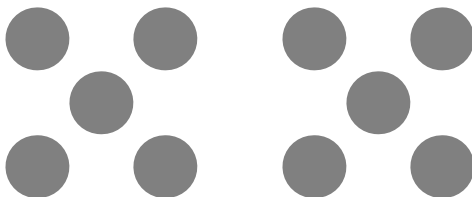
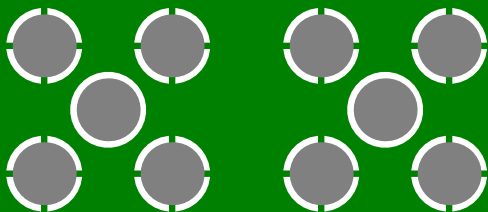
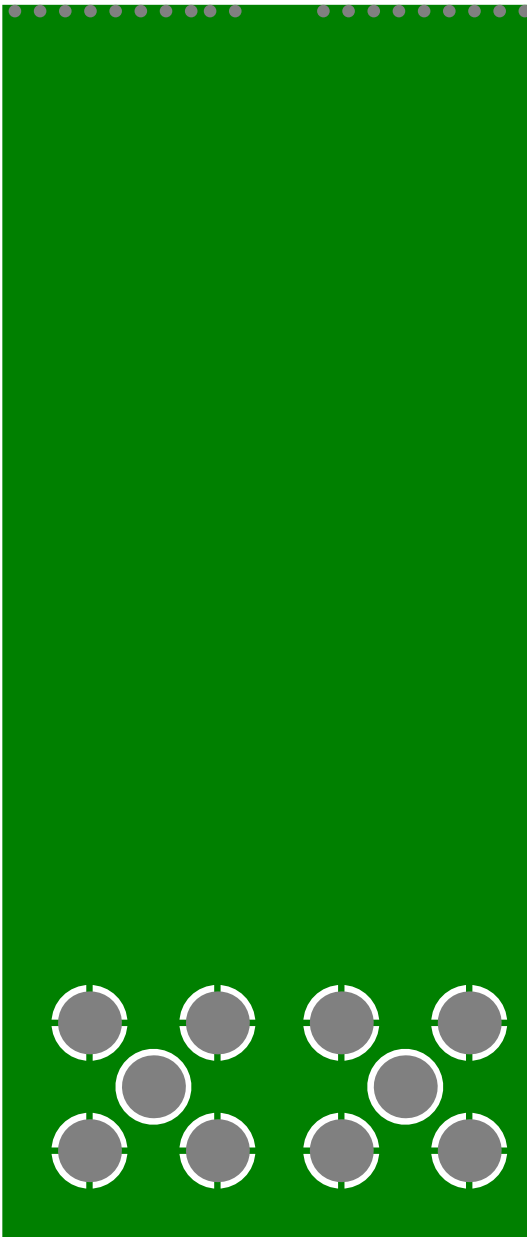


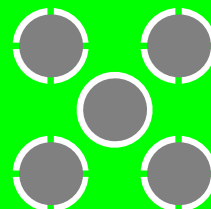
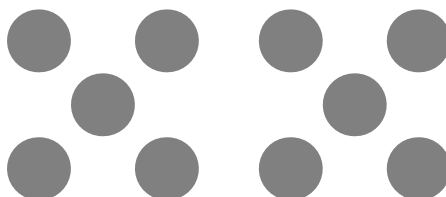
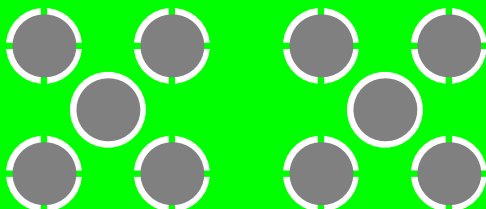
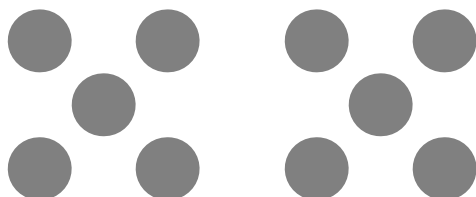
Test Board of  
Differential pairs  
by Michal Karas  
Poland 2024

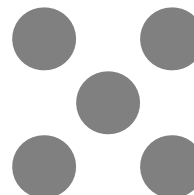
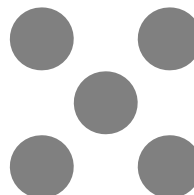
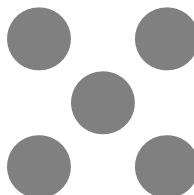
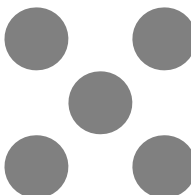
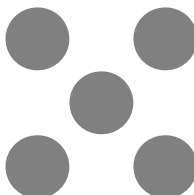
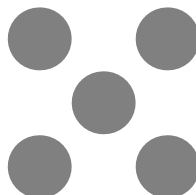
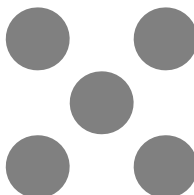
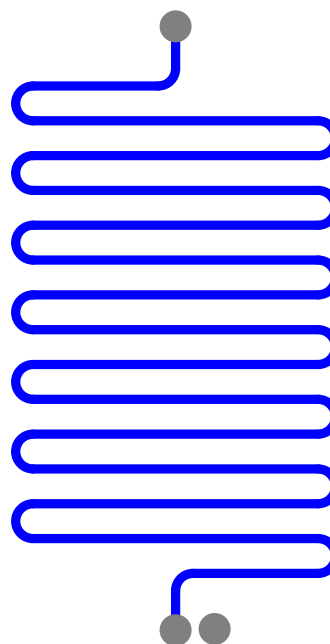


Diff length 2800ps - 3100ps






















# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.50mil	3.8
4		Top Layer	Copper	1.38mil	
5		Dielectric 1	7628	8.28mil	4.4
6		Mid Layer 1	Copper	0.69mil	
7		Core	FR-4	41.93mil	4.5
8		Mid Layer 2	Copper	0.69mil	
9		Dielectric 2	7628	8.28mil	4.4
10		Bottom Layer	Copper	1.38mil	
11		Bottom Solder	Solder Resist	0.50mil	3.8
12		Bottom Overlay			
13		Bottom Paste			
	Height : 63.63mil				